



Material Content Data Sheet



Sales Product Name		IPD30N10S3L-34		Issued		29. August 2013		
MA#		MA000391968						
Package		PG-TO252-3-11		Weight*		370.29 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.295	0.62	0.62	6199	6199
leadframe	non noble metal	iron	7439-89-6	0.234	0.06		633	
	inorganic material	phosphorus	7723-14-0	0.070	0.02		190	
	non noble metal	copper	7440-50-8	234.187	63.26	63.34	632447	633270
wire	non noble metal	aluminium	7429-90-5	1.879	0.51	0.51	5076	5076
encapsulation	organic material	carbon black	1333-86-4	1.258	0.34		3396	
	plastics	epoxy resin	-	22.008	5.94		59435	
	inorganic material	silicondioxide	60676-86-0	102.494	27.68	33.96	276797	339629
leadfinish	non noble metal	tin	7440-31-5	3.740	1.01	1.01	10100	10100
plating	non noble metal	nickel	7440-02-0	0.091	0.02		245	
	inorganic material	phosphorus	7723-14-0	0.000	0.00	0.02	1	246
solder	non noble metal	tin	7440-31-5	0.041	0.01		110	
	noble metal	silver	7440-22-4	0.051	0.01		137	
	non noble metal	lead	7439-92-1	1.938	0.52	0.54	5234	5481
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

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